

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding
Frames

EXAMINER INTERVIEW SUMMARY OF FEBRUARY 6, 2003

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: D. Brent Kenady
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Applicant's representative held an interview with Examiner Tugbang on February 6, 2003. Applicant's representative would like to thank Examiner Tugbang for his time and attention to this matter.

The Examiner requested an election from numerous alleged species of the pending claims. No agreement was reached, and therefore no election was made.

Respectfully submitted,

Dated: 2-11-03By: D. Brent Kenady
Reg. No. 40,045

Practitioner's Docket No. MI22-1839

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Farnworth et al, Warren M.

Application No.: 10/004,172

Group No.: 3729

Filed: 10/09/01

Examiner: D. Tugbang

For: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding Frames

Assistant Commissioner for Patents
Washington, D.C. 20231

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CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being facsimile transmitted to the Patent and Trademark Office at (703) 872-9301 on the date shown below:

Examiner Interview Summary of February 6, 2003

2/11/03
Date

Robin Saldivia


Signature

TOTAL PAGES - 2

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